EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	129348	(lap$4 grind$3 thin$4 polish$3 etch$3) with wafer$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/19 22:50
L2	3549	1 and (bump$3 with (solder$3 electrode$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/19 22:37
L3	2170	2 and ((dic$3 singulat$4 separat$4 divid$3 cut$4) with (chip$1 die$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/19 22:37
L5	233	3 and ((heat thermal) with (Cu copper))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/19 22:38
L9	779	1 same (bump$3 with (solder$3 electrode$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/19 22:37
L10	385	9 and ((dic$3 singulat$4 separat$4 divid$3 cut$4) with (chip$1 die$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/19 22:37
L11	30	10 and ((heat thermal) with (Cu copper))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/19 22:38